

CLAIMS

I claim:

1. A semiconductor package comprising:

a semiconductor die having first and second principal surfaces;

a heat sink attached to a first surface of the die;

a lead attached to a second surface of the die, the lead extending over opposite edges of the die, a notch being formed in the lead on a side of the lead facing the die, the notch being located where the lead passes over an edge of the die; and

a nonconductive capsule encasing the die and at least a portion of the lead and the heat sink, opposite ends of the lead protruding from the capsule.

2. The semiconductor package of Claim 1 wherein the lead is symmetrical about an axis of the side.

3. The semiconductor package of Claim 2 wherein a first notch is formed in the lead where the lead passes over a first edge of the die and a second notch is formed in the lead where the lead passes over a second edge of the die.